# Kingbright

Optoelectronic Components

Soldering

General Notes

1. We recommend manual soldering operations only for repair and rework purposes. The soldering iron should not exceed 30W in power. The maximum soldering temperature is 300°C for Pb-Sn solder and 350°C for lead-free solder for normal lamps and displays. For blue (425nm),and blue-green (525nm) LEDs, the maximum soldering iron temperature is 280°C. Do not place the soldering iron on the component for more than 3 seconds.

Keep Solder Paste Smoothly

2. The tip of soldering iron should never touch the lens epoxy.

3. Do not apply stress to the leads when the component is heated above 85°C otherwise internal wire bonds may be damaged.

4. SMD products must be mounted according to specified soldering pad patterns. Refer to the product datasheet for details. Solder paste must be evenly applied to each soldering pad to insure proper bonding and positioning of the component.
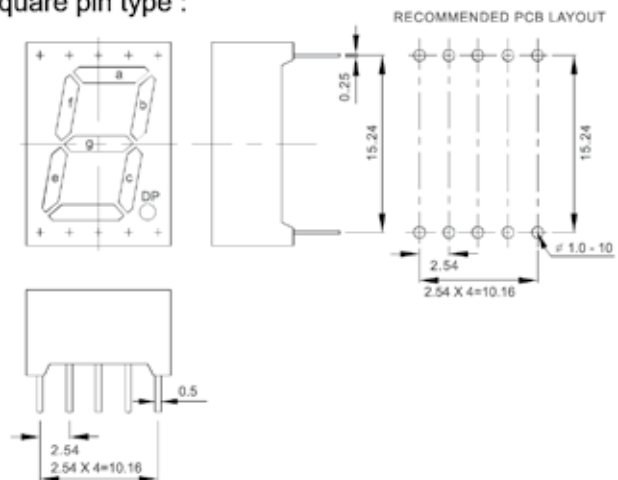
Uneven Solder Coating
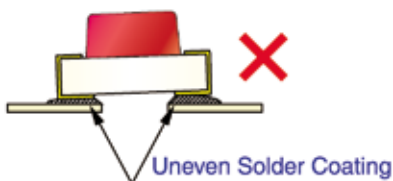
5. After soldering, allow at least three minutes for the component to cool to room temperature before further operations.

Recommended PCB pin hole diameters for display products are list below :
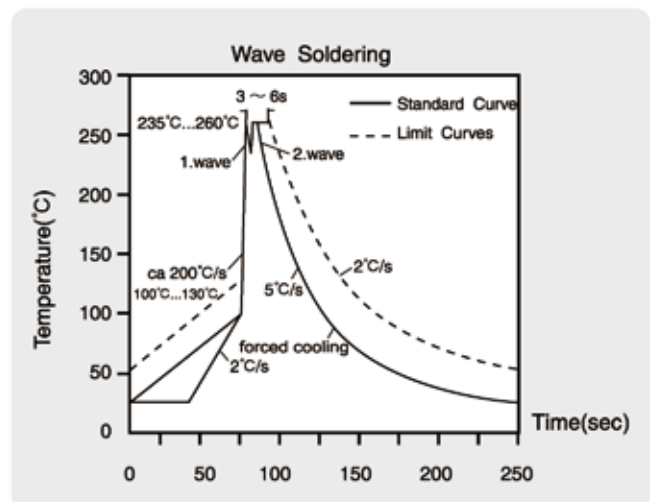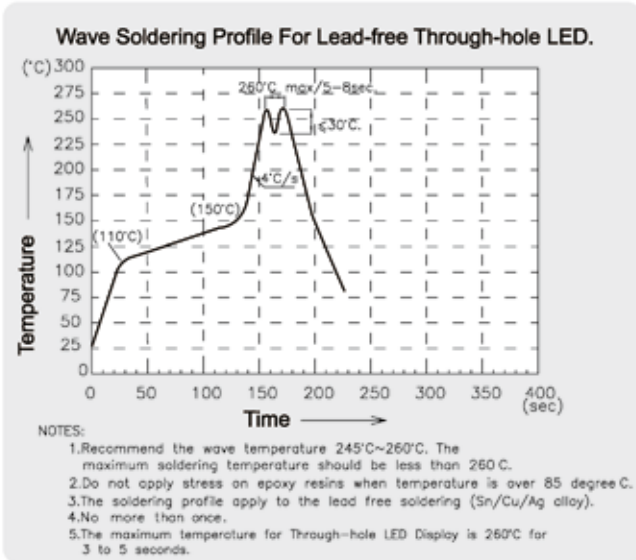Round pin type : 2 x pin diameters
Square pin type :

RECOMMENDED PCB LAYOUT

Recommended Wave Soldering Profiles For Kingbright Through-Hole Products

1. Wave Soldering Profile With Pb-Sn Solder

Wave Soldering

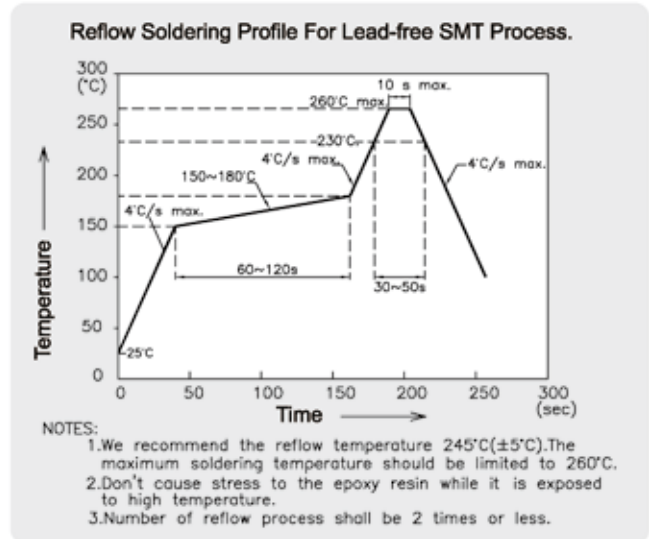## 2. Lead-Free Wave Soldering Profile

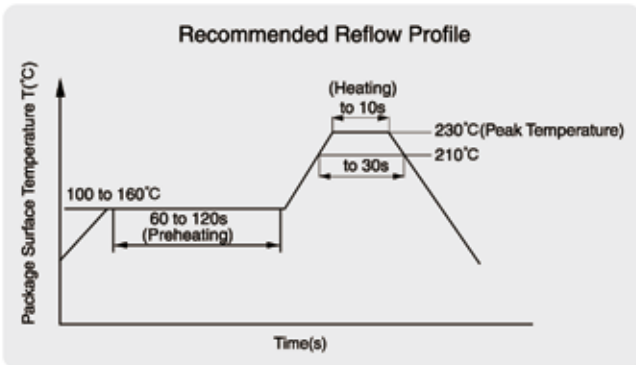Wave Soldering Profile For Lead-free Through-hole LED.

NOTES:
1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260 C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.
5. The maximum temperature for Through-hole LED Display is 260°C for 3 to 5 seconds.

Recommended Reflow Soldering Profiles For Kingbright SMD Products

1. Reflow Soldering Profile With Pb-Sn Solder

No more than two soldering passes with the recommended profile.

Recommended Reflow Profile

2. Lead-Free Reflow Soldering Profile

No more than two soldering passes with the recommended profile.

Reflow Soldering Profile For Lead-free SMT Process.

NOTES:
1. We recommend the reflow temperature 245°C(±5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Static Electricity and Voltage Spikes in InGaN/GaN Products

InGaN/GaN products are sensitive to electrostatic discharge (ESD) and other transient voltage spikes. ESD and voltage spikes can affect the component's reliability, increase reverse current, and decrease forward voltage. This may result in reduced light intensity or cause component failure.

Kingbright InGaN/GaN products are stored in anti-static packaging for protection during transport and storage. Please note the anti-static measures below when handling Kingbright InGaN/GaN products:

136

Design Precautions

Products using InGaN/GaN components must incorporate protection circuitry to prevent ESD and voltage spikes from reaching the vulnerable component.

ESD Protection During Production

Static discharge can result when static-sensitive products come in contact with the operator or other conductors. The following procedures may decrease the possibility of ESD damage:

1. Minimize friction between the product and surroundings to avoid static buildup.
2. All production machinery and test instruments must be electrically grounded.
3. Operators must wear anti-static bracelets.
4. Wear anti-static suit when entering work areas with conductive machinery.
5. Set up ESD protection areas using grounded metal plating for component handling.
6. All workstations that handle IC and ESD-sensitive components must maintain an electrostatic potential of 150V or less.
7. Maintain a humidity level of 50% or higher in production areas.
8. Use anti-static packaging for transport and storage.
9. All anti-static equipment and procedures should be periodically inspected and evaluated for proper functionality.

LED Mounting Method

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)
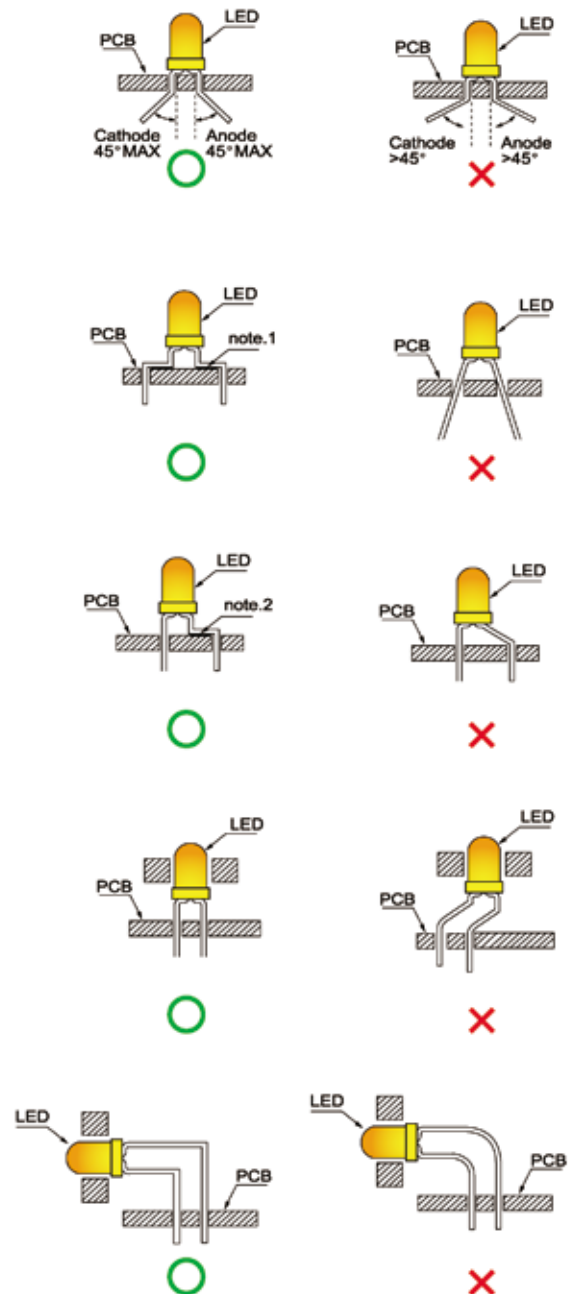
Fig. 1

"○" Correct mounting method
"✗" Incorrect mounting method
Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig. 2)
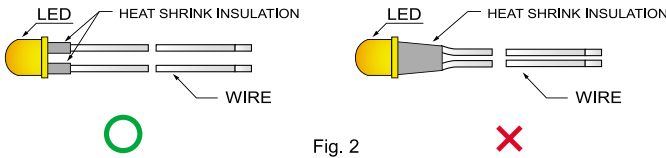

Fig. 2

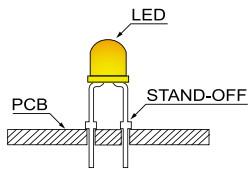3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.
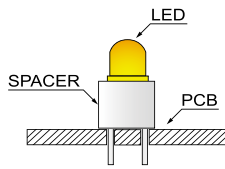

Fig. 3   Fig. 4

Lead Forming Procedures

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
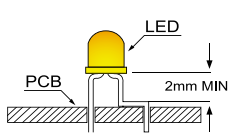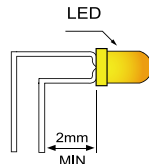

Fig. 5   Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after soldering.

3. Do not stress the LED lens during lead-forming in order to prevent fractures in the lens epoxy and damage the internal structures.

4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
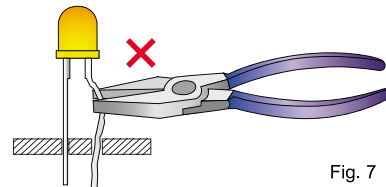

Fig. 7
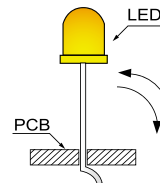
5. Do not bend the leads more than twice. (Fig. 8)

Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50° C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.
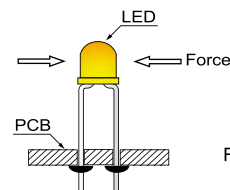

Fig. 9

Cleaning

1. Do not use harsh organic solvents such as trichloro-ethylene, acetone, Chlorosen, and Diflon S3MC for cleaning because they may cloud or damage the LED lens.
2. Isopropyl alcohol or deionized water are recommended solvents for cleaning.
3. Special attention should be taken if other chemicals are used for cleaning because other solvents may damage the epoxy in the lens or housing.
4. The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
5. When water is used in the cleaning process, immediately remove excess moisture from the LED via forced-air drying afterwards.

Miscellaneous Design Notes

1. Protective current-limiting resistors may be necessary to operate the LEDs within the specified range.

2. LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.
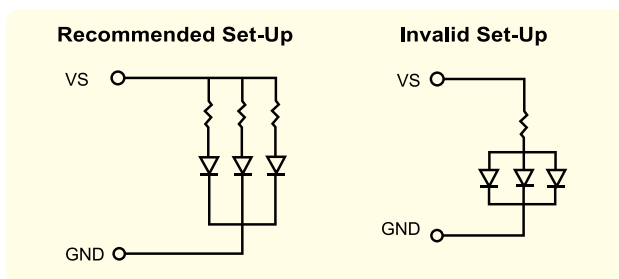
3. The driving circuit should be designed to avoid reverse voltages and transient voltage spikes when the circuit is powered up or shut down.

4. During soldering, SMD components should be mounted such that the leads are placed perpendicular to the direction of PCB travel to insure the solder on each lead melts simultaneously during reflow.
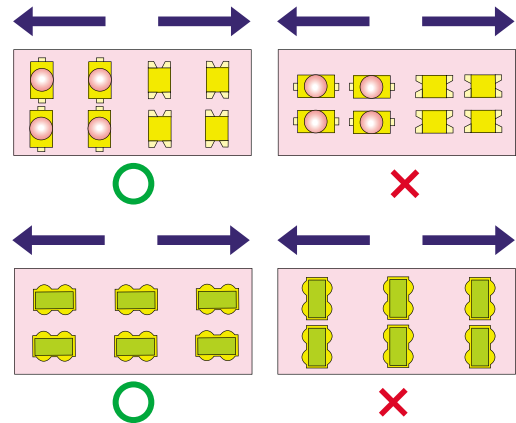
5. Optimal usage of high-power LED devices requires careful design by the end-user to optimize heat dissipation, such as increasing the size of the metal backing around the soldering pad. Refer to the product datasheet for specific design recommendations regarding heat dissipation.
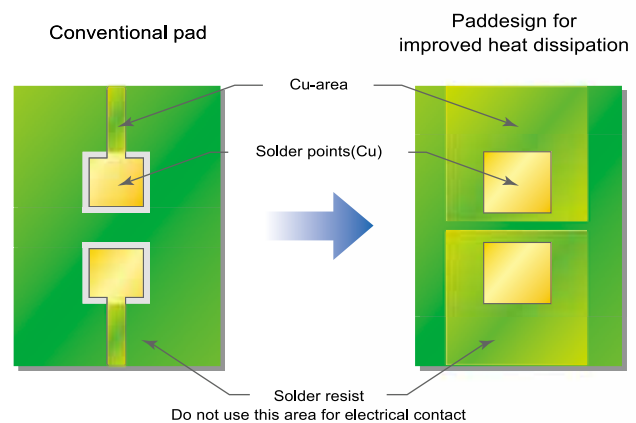
6. High temperatures can reduce device performance and reliability. Keep LED devices away from heat sources for best performance.

Restrictions on Product Use

1. The information contained within this document is subject to change without notice. Before referencing this document, please confirm that it is the most current version available.
2. Not all devices and product families are available in every country.
3. The light output from UV, blue, white, and other high-power LEDs may cause injury to the human eye when viewed directly.
4. LED devices may contain gallium arsenide (GaAs) material. GaAs is harmful if ingested.
   GaAs dust and fumes are toxic. Do not break, cut, or pulverize LED devices. Do not dissolve LEDs in chemical solvents.
5. Semiconductor devices can fail or malfunction due to their sensitivity to electrical fluctuation and physical stress. It is the responsibility of the user to observe all safety standards when using Kingbright products, in order to avoid situations in which the malfunction or failure of a Kingbright product could cause injury, property damage, or the loss of human life. In developing designs, please insure that Kingbright products are used within specified operating conditions as set forth in the most recent product specification datasheet.

White Bin Code
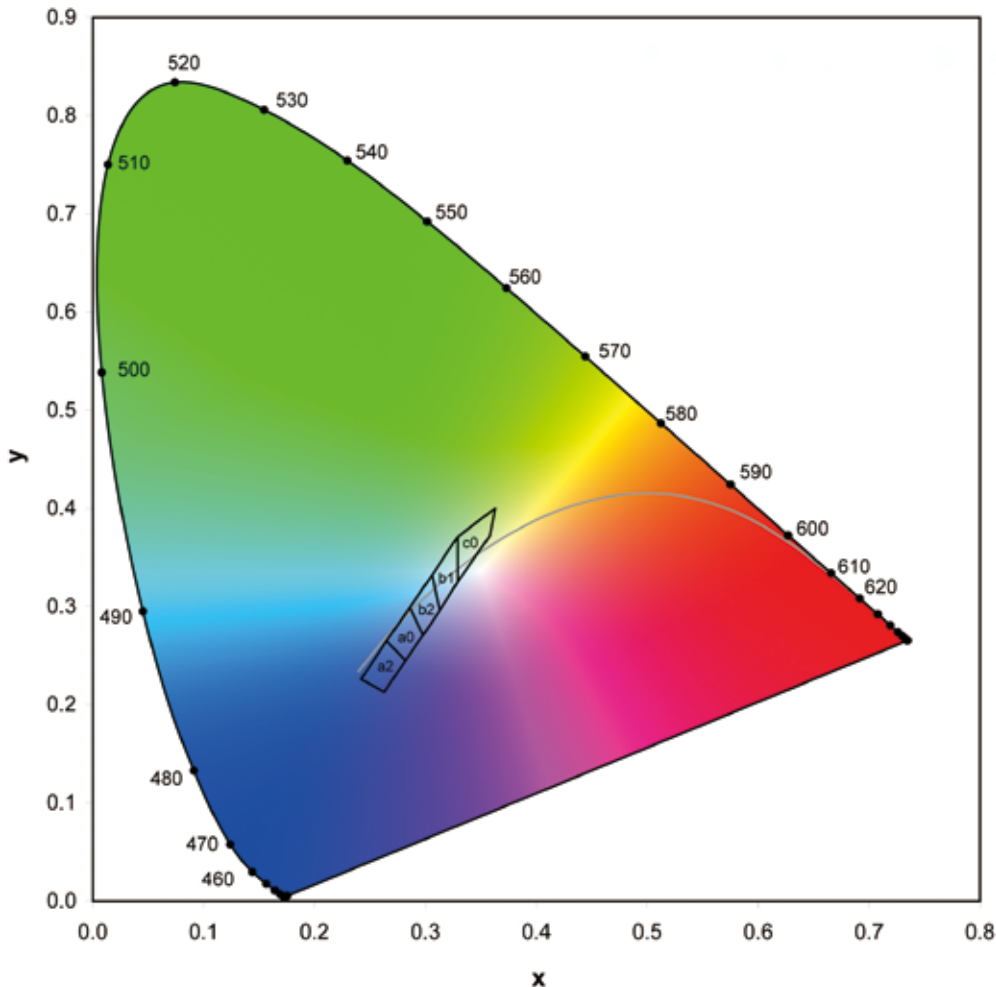
Bin	x	y
a2	0.263	0.213
	0.282	0.245
	0.265	0.265
	0.242	0.226
CCT: 15000K~		
a0	0.282	0.245
	0.298	0.271
	0.286	0.299
	0.265	0.265
CCT: 9000~15000K		
b2	0.298	0.271
	0.313	0.296
	0.306	0.332
	0.286	0.299
CCT: 6800~9000K		
b1	0.313	0.296
	0.329	0.325
	0.329	0.371
	0.306	0.332
CCT: 5600~6800K		
c0	0.329	0.325
	0.358	0.372
	0.363	0.400
	0.329	0.371
CCT: 4600~5600K		

CCT2500 ~ 7000 K Bin Code
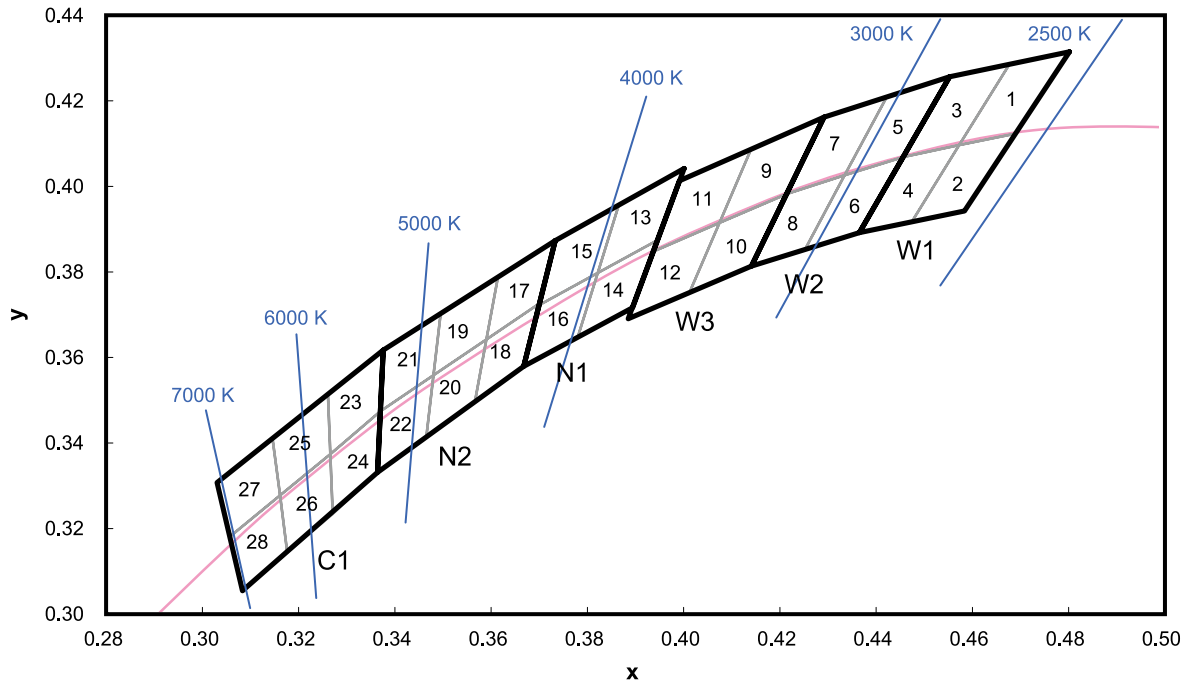
Group	Chromaticity Regions	CCT(K) Min.	Typ.	Max.
W1	1, 2, 3, 4	2580	2700	2870
W2	5, 6, 7, 8	2870	3000	3220
W3	9, 10, 11, 12	3220	3500	3710
N1	13, 14, 15, 16	3710	4000	4260
N2	17, 18, 19, 20, 21, 22	4260	4700	5310
C1	23, 24, 25, 26, 27, 28	5310	6000	7040

	x	y		x	y		x	y		x	y
1	0.4582	0.4099	8	0.4147	0.3814	15	0.3702	0.3722	22	0.3481	0.3557
	0.4687	0.4289		0.4221	0.3984		0.3736	0.3874		0.3370	0.3472
	0.4813	0.4319		0.4342	0.4028		0.3869	0.3958		0.3361	0.3328
	0.4700	0.4126		0.4259	0.3853		0.3825	0.3798		0.3466	0.3411
2	0.4483	0.3919	9	0.4080	0.3916	16	0.3670	0.3578	23	0.3376	0.3616
	0.4582	0.4099		0.4146	0.4089		0.3702	0.3722		0.3260	0.3512
	0.4700	0.4126		0.4299	0.4165		0.3825	0.3798		0.3265	0.3371
	0.4593	0.3944		0.4221	0.3984		0.3783	0.3646		0.3370	0.3472
3	0.4465	0.4071	10	0.4017	0.3751	17	0.3736	0.3874	24	0.3370	0.3472
	0.4562	0.4260		0.4080	0.3916		0.3616	0.3788		0.3265	0.3371
	0.4687	0.4289		0.4221	0.3984		0.3592	0.3641		0.3270	0.3230
	0.4582	0.4099		0.4147	0.3814		0.3703	0.3726		0.3364	0.3328
4	0.4373	0.3893	11	0.3941	0.3848	18	0.3703	0.3726	25	0.3260	0.3512
	0.4465	0.4071		0.3996	0.4015		0.3592	0.3641		0.3144	0.3408
	0.4582	0.4099		0.4146	0.4089		0.3568	0.3495		0.3160	0.3274
	0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3265	0.3371
5	0.4342	0.4028	12	0.3889	0.3690	19	0.3616	0.3788	26	0.3265	0.3371
	0.4430	0.4212		0.3941	0.3848		0.3496	0.3702		0.3160	0.3274
	0.4562	0.4260		0.4080	0.3916		0.3481	0.3557		0.3175	0.3139
	0.4465	0.4071		0.4017	0.3751		0.3592	0.3641		0.3270	0.3230
6	0.4259	0.3853	13	0.3825	0.3798	20	0.3592	0.3641	27	0.3144	0.3408
	0.4342	0.4028		0.3869	0.3958		0.3481	0.3557		0.3028	0.3304
	0.4465	0.4071		0.4006	0.4044		0.3466	0.3411		0.3055	0.3177
	0.4373	0.3893		0.3950	0.3875		0.3568	0.3495		0.3160	0.3274
7	0.4221	0.3984	14	0.3783	0.3646	21	0.3496	0.3702	28	0.3160	0.3274
	0.4299	0.4165		0.3825	0.3798		0.3376	0.3616		0.3055	0.3177
	0.4430	0.4212		0.3950	0.3875		0.3370	0.3472		0.3081	0.3049
	0.4342	0.4028		0.3898	0.3716		0.3481	0.3557		0.3175	0.3139